

Integrated Relay, Inductive Load Driver

NUD3105

This device is used to switch inductive loads such as relays, solenoids incandescent lamps, and small DC motors without the need of a free-wheeling diode. The device integrates all necessary items such as the MOSFET switch, ESD protection, and Zener clamps. It accepts logic level inputs thus allowing it to be driven by a large variety of devices including logic gates, inverters, and microcontrollers.

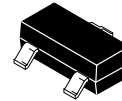
Features

- Provides a Robust Driver Interface Between DC Relay Coil and Sensitive Logic Circuits
- Optimized to Switch Relays from 3.0 V to 5.0 V Rail
- Capable of Driving Relay Coils Rated up to 2.5 W at 5.0 V
- Internal Zener Eliminates the Need of Free-Wheeling Diode
- Internal Zener Clamp Routes Induced Current to Ground for Quieter Systems Operation
- Low $V_{DS(on)}$ Reduces System Current Drain
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and Halide Free

Typical Applications

- Telecom: Line Cards, Modems, Answering Machines, FAX
- Computers and Office: Photocopiers, Printers, Desktop Computers
- Consumer: TVs and VCRs, Stereo Receivers, CD Players, Cassette Recorders
- Industrial: Small Appliances, Security Systems, Automated Test Equipment, Garage Door Openers
- Automotive: 5.0 V Driven Relays, Motor Controls, Power Latches, Lamp Drivers

RELAY/INDUCTIVE LOAD DRIVER 0.5 AMPERE, 8.0 VOLT CLAMP

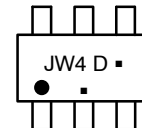
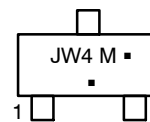


SOT-23
(TO-236)
CASE 318



SC-74
CASE 318F
STYLE 7

MARKING DIAGRAMS



JW4 = Device Code
M = Date Code*
D = Date Code
▪ = Pb-Free Package

(Note: Microdot may be in either location)
*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping†
NUD3105LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel
NUD3105DMT1G	SOT-74 (Pb-Free)	3000 / Tape & Reel
SZNUD3105DMT1G	SOT-74 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

NUD3105

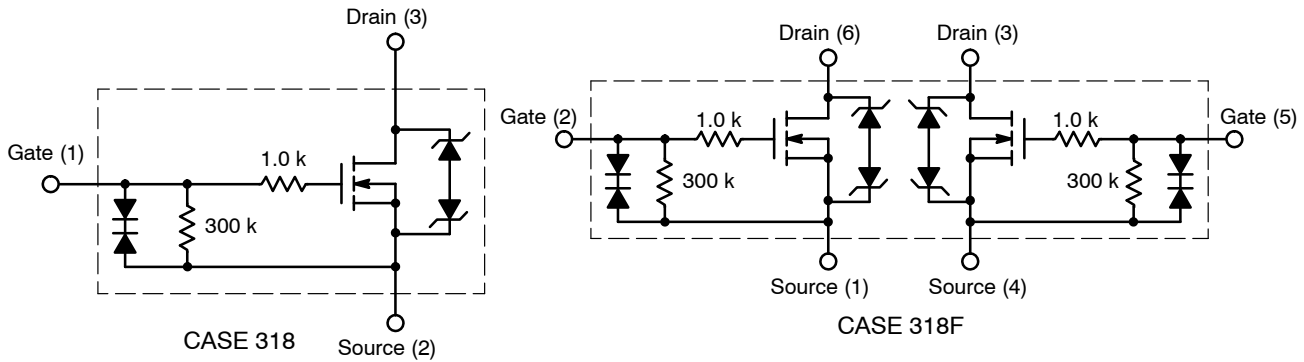


Figure 1. Internal Circuit Diagrams

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Rating	Value	Unit
V_{DSS}	Drain to Source Voltage – Continuous	6.0	V_{dc}
V_{GS}	Gate to Source Voltage – Continuous	6.0	V_{dc}
I_D	Drain Current – Continuous	500	mA
E_z	Single Pulse Drain-to-Source Avalanche Energy ($T_{Jinitial} = 25^\circ\text{C}$) (Note 2)	50	mJ
E_{zpk}	Repetitive Pulse Zener Energy Limit ($DC \leq 0.01\%$) ($f = 100\text{ Hz}$, $DC = 0.5$)	4.5	mJ
T_J	Junction Temperature	150	$^\circ\text{C}$
T_A	Operating Ambient Temperature	-40 to 85	$^\circ\text{C}$
T_{stg}	Storage Temperature Range	-65 to +150	$^\circ\text{C}$
P_D	Total Power Dissipation (Note 1) Derating Above 25°C	SOT-23 225 1.8	mW mW/ $^\circ\text{C}$
	Total Power Dissipation (Note 1) Derating Above 25°C	SC-74 380 1.5	mW mW/ $^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	SOT-23 556	$^\circ\text{C}/\text{W}$
		SC-74 329	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- This device contains ESD protection and exceeds the following tests:
Human Body Model 2000 V per MIL_STD-883, Method 3015.
Machine Model Method 200 V.

- Refer to the section covering Avalanche and Energy.

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Characteristic	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
V_{BRDSS}	Drain to Source Sustaining Voltage (Internally Clamped), ($I_D = 10\text{ mA}$)	6.0	8.0	9.0	V
B_{VGS0}	$I_g = 1.0\text{ mA}$	-	-	8.0	V
I_{DSS}	Drain to Source Leakage Current ($V_{DS} = 5.5\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 25^\circ\text{C}$) ($V_{DS} = 5.5\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 85^\circ\text{C}$)	-	-	15	μA
		-	-	15	
I_{GSS}	Gate Body Leakage Current (318) ($V_{GS} = 3.0\text{ V}$, $V_{DS} = 0\text{ V}$) ($V_{GS} = 5.0\text{ V}$, $V_{DS} = 0\text{ V}$)	5.0	-	19	μA
		-	-	50	
I_{GSS}	Gate Body Leakage Current (318F) ($V_{GS} = 3.0\text{ V}$, $V_{DS} = 0\text{ V}$) ($V_{GS} = 5.0\text{ V}$, $V_{DS} = 0\text{ V}$)	5.0	-	35	μA
		-	-	65	

NUD3105

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted) (continued)

Symbol	Characteristic	Min	Typ	Max	Unit
ON CHARACTERISTICS					
$V_{GS(th)}$	Gate Threshold Voltage ($V_{GS} = V_{DS}$, $I_D = 1.0\text{ mA}$) ($V_{GS} = V_{DS}$, $I_D = 1.0\text{ mA}$, $T_J = 85^\circ\text{C}$)	0.8 0.8	1.2 -	1.4 1.4	V
$R_{DS(on)}$	Drain to Source On-Resistance ($I_D = 250\text{ mA}$, $V_{GS} = 3.0\text{ V}$) ($I_D = 500\text{ mA}$, $V_{GS} = 3.0\text{ V}$) ($I_D = 500\text{ mA}$, $V_{GS} = 5.0\text{ V}$) ($I_D = 500\text{ mA}$, $V_{GS} = 3.0\text{ V}$, $T_J = 85^\circ\text{C}$) ($I_D = 500\text{ mA}$, $V_{GS} = 5.0\text{ V}$, $T_J = 85^\circ\text{C}$)	- - - - -	- - - - -	1.2 1.3 0.9 1.3 0.9	Ω
$I_{DS(on)}$	Output Continuous Current ($V_{DS} = 0.25\text{ V}$, $V_{GS} = 3.0\text{ V}$) ($V_{DS} = 0.25\text{ V}$, $V_{GS} = 3.0\text{ V}$, $T_J = 85^\circ\text{C}$)	300 200	400 -	- -	mA
g_{FS}	Forward Transconductance ($V_{OUT} = 5.0\text{ V}$, $I_{OUT} = 0.25\text{ A}$)	350	570	-	mmhos

DYNAMIC CHARACTERISTICS

C_{iss}	Input Capacitance ($V_{DS} = 5.0\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 10\text{ kHz}$)	-	25	-	pF
C_{oss}	Output Capacitance ($V_{DS} = 5.0\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 10\text{ kHz}$)	-	37	-	pF
C_{rss}	Transfer Capacitance ($V_{DS} = 5.0\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 10\text{ kHz}$)	-	8.0	-	pF

SWITCHING CHARACTERISTICS

t_{PHL} t_{PLH}	Propagation Delay Times: High to Low Propagation Delay; Figure 1 (5.0 V) Low to High Propagation Delay; Figure 1 (5.0 V)	- -	25 80	- -	nS
t_{PHL} t_{PLH}	High to Low Propagation Delay; Figure 1 (3.0 V) Low to High Propagation Delay; Figure 1 (3.0 V)	- -	44 44	- -	nS
t_f t_r	Transition Times: Fall Time; Figure 1 (5.0 V) Rise Time; Figure 1 (5.0 V)	- -	23 32	- -	nS
t_f t_r	Fall Time; Figure 1 (3.0 V) Rise Time; Figure 1 (3.0 V)	- -	53 30	- -	nS

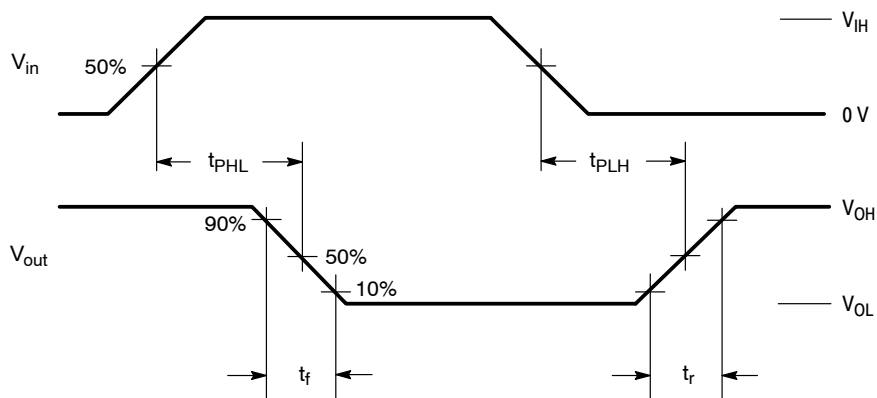


Figure 1. Switching Waveforms

TYPICAL CHARACTERISTICS

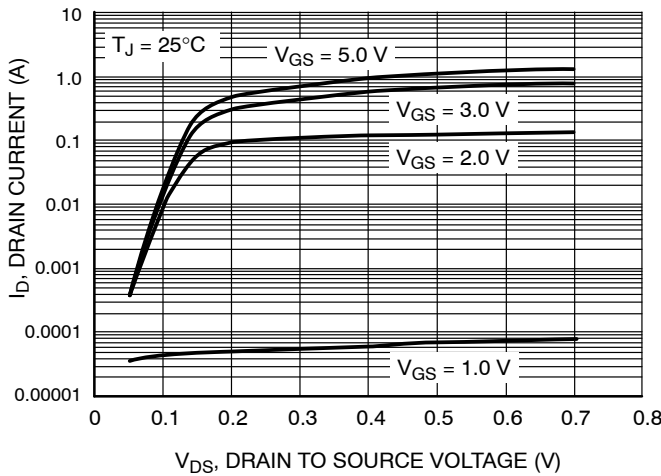


Figure 2. Output Characteristics

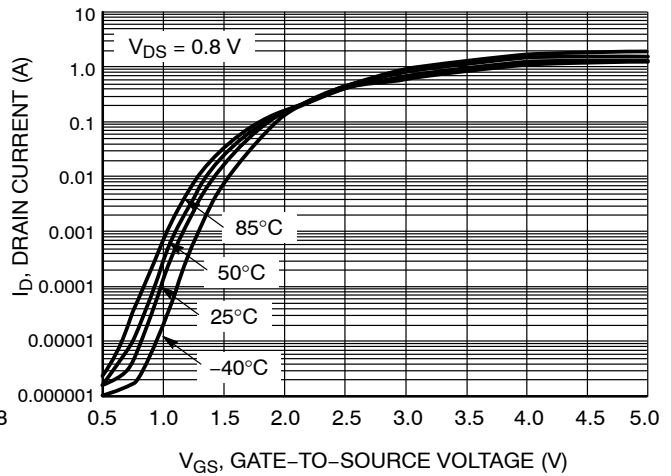


Figure 3. Transfer Function

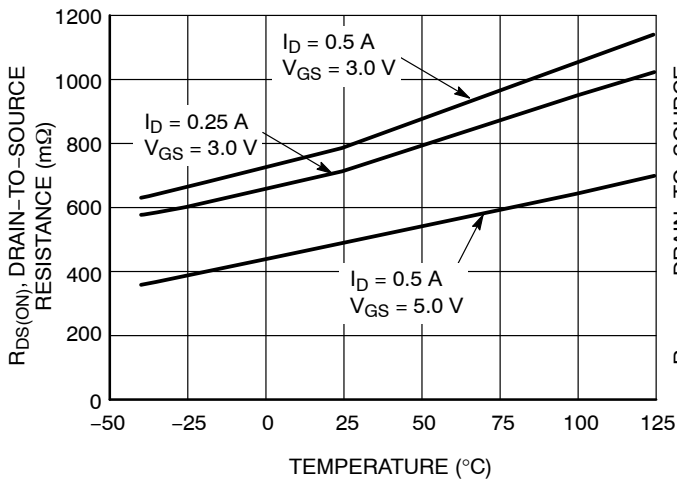


Figure 4. On Resistance Variation vs. Temperature

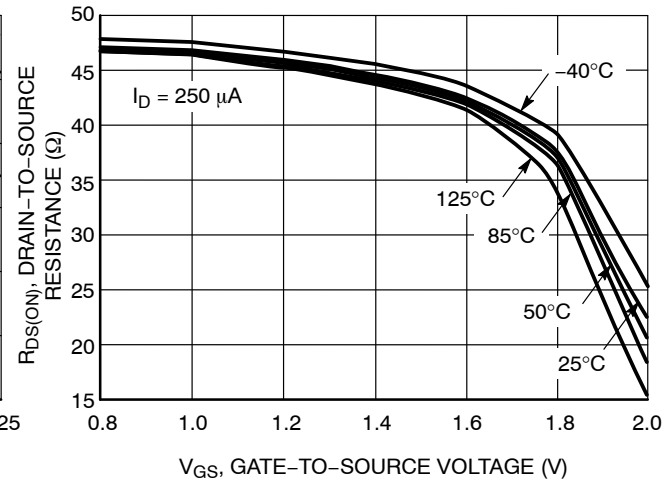


Figure 5. $R_{DS(ON)}$ Variation with Gate-To-Source Voltage

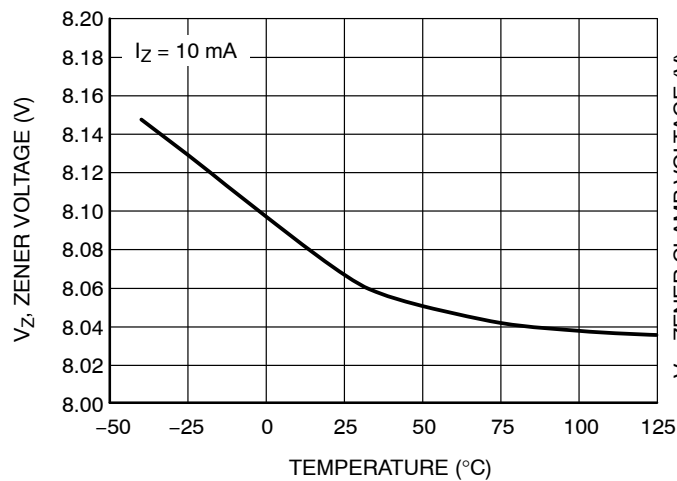


Figure 6. Zener Voltage vs. Temperature

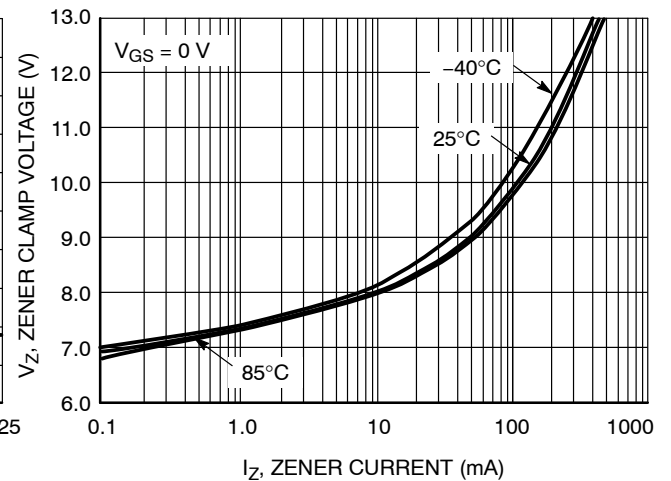


Figure 7. Zener Clamp Voltage vs. Zener Current

NUD3105

TYPICAL CHARACTERISTICS (continued)

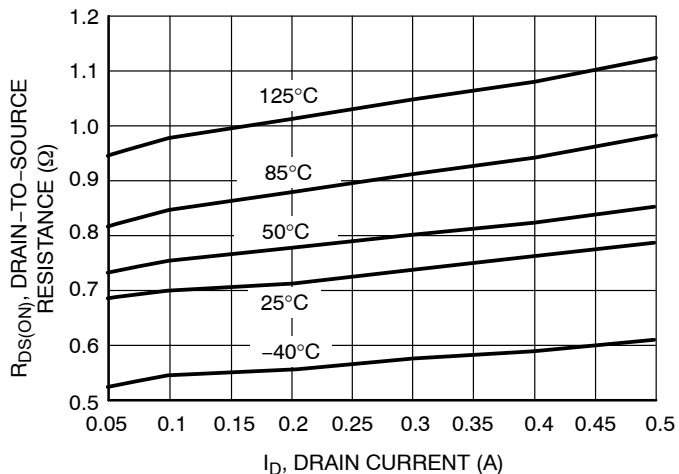


Figure 8. On-Resistance vs. Drain Current and Temperature

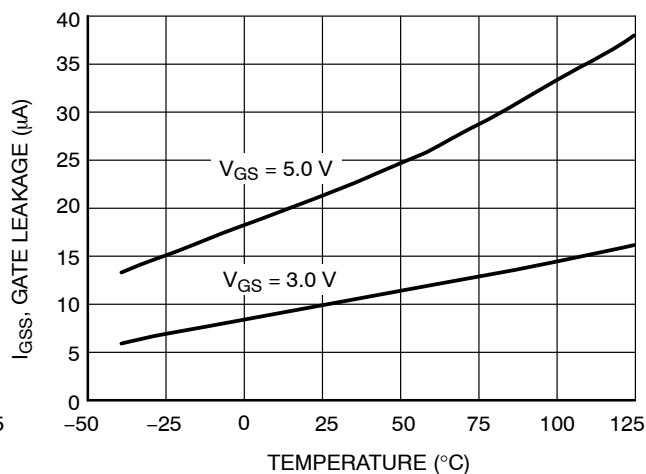


Figure 9. Gate Leakage vs. Temperature

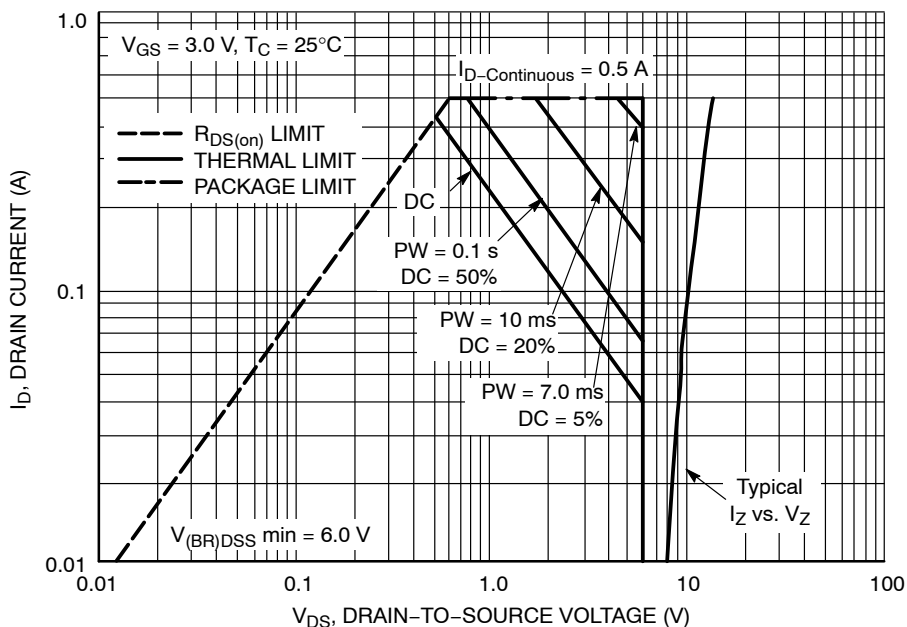


Figure 10. Safe Operating Area

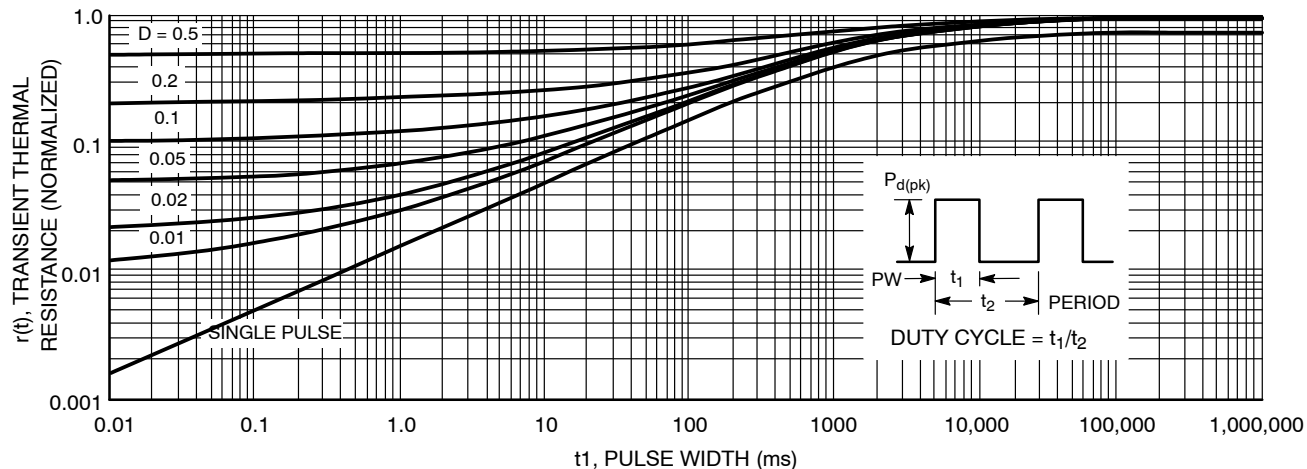


Figure 11. Transient Thermal Response

NUD3105

Max Continuous Current Calculation

for TX2-5V Relay, $R_1 = 178 \Omega$ Nominal @ $R_A = 25^\circ\text{C}$

Assuming $\pm 10\%$ Make Tolerance,

$R_1 = 178 \Omega * 0.9 = 160 \Omega$ Min @ $T_A = 25^\circ\text{C}$

T_C for Annealed Copper Wire is $0.4\%/^\circ\text{C}$

$R_1 = 160 \Omega * [1 + (0.004) * (-40^\circ - 25^\circ)] = 118 \Omega$ Min @ -40°C

$I_O \text{ Max} = (5.5 \text{ V Max} - 0.25\text{V}) / 118 \Omega = 45 \text{ mA}$

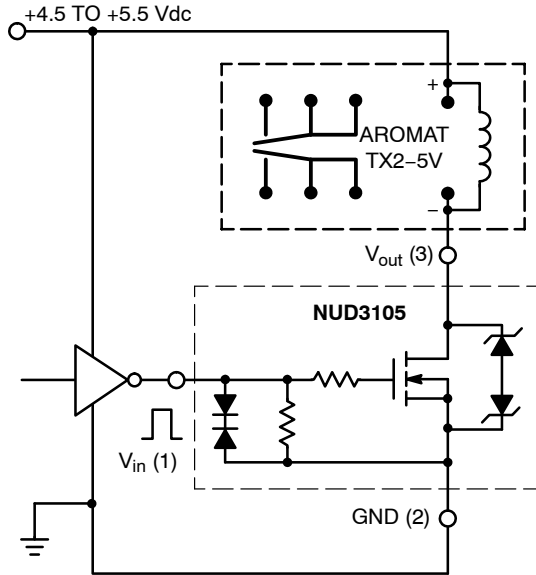


Figure 13. A 140 mW, 5.0 V Relay with TTL Interface

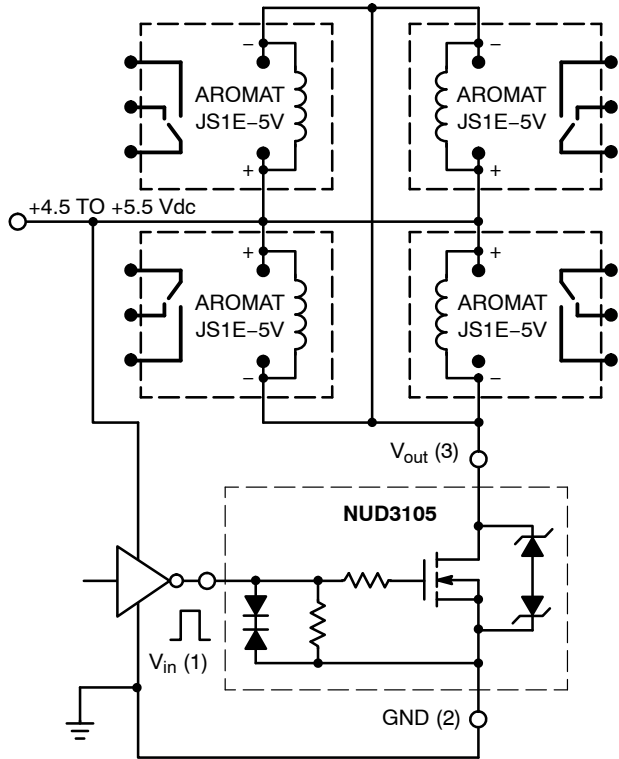
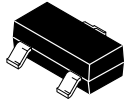


Figure 14. A Quad 5.0 V, 360 mW Coil Relay Bank

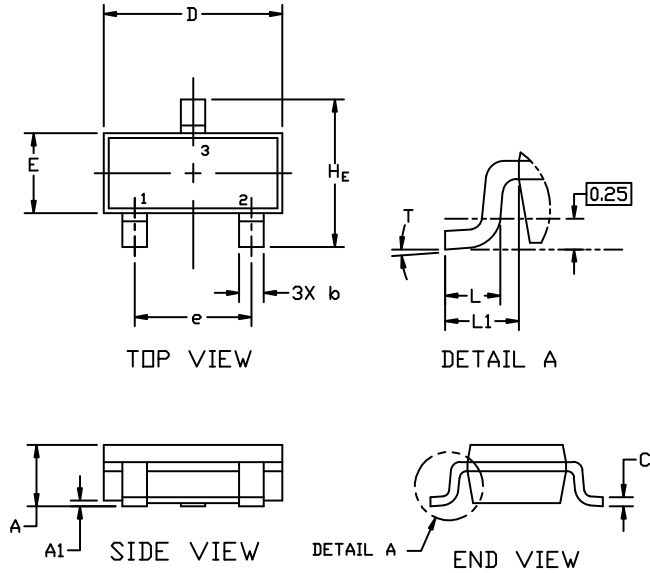
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SOT-23 (TO-236)
CASE 318
ISSUE AT

DATE 01 MAR 2023

SCALE 4:1



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

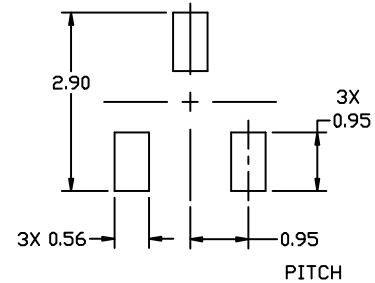
DIM	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
c	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
H _E	2.10	2.40	2.64	0.083	0.094	0.104
T	0°	---	10°	0°	---	10°

GENERIC MARKING DIAGRAM*



- XXX = Specific Device Code
- M = Date Code
- = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.



RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

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MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



SOT-23 (TO-236)
CASE 318
ISSUE AT

DATE 01 MAR 2023

- | | | | | | |
|---|---|---|---|---|---|
| STYLE 1 THRU 5:
CANCELLED | STYLE 6:
PIN 1. BASE
2. EMITTER
3. COLLECTOR | STYLE 7:
PIN 1. EMITTER
2. BASE
3. COLLECTOR | STYLE 8:
PIN 1. ANODE
2. NO CONNECTION
3. CATHODE | | |
| STYLE 9:
PIN 1. ANODE
2. ANODE
3. CATHODE | STYLE 10:
PIN 1. DRAIN
2. SOURCE
3. GATE | STYLE 11:
PIN 1. ANODE
2. CATHODE
3. CATHODE-ANODE | STYLE 12:
PIN 1. CATHODE
2. CATHODE
3. ANODE | STYLE 13:
PIN 1. SOURCE
2. DRAIN
3. GATE | STYLE 14:
PIN 1. CATHODE
2. GATE
3. ANODE |
| STYLE 15:
PIN 1. GATE
2. CATHODE
3. ANODE | STYLE 16:
PIN 1. ANODE
2. CATHODE
3. CATHODE | STYLE 17:
PIN 1. NO CONNECTION
2. ANODE
3. CATHODE | STYLE 18:
PIN 1. NO CONNECTION
2. CATHODE
3. ANODE | STYLE 19:
PIN 1. CATHODE
2. ANODE
3. CATHODE-ANODE | STYLE 20:
PIN 1. CATHODE
2. ANODE
3. GATE |
| STYLE 21:
PIN 1. GATE
2. SOURCE
3. DRAIN | STYLE 22:
PIN 1. RETURN
2. OUTPUT
3. INPUT | STYLE 23:
PIN 1. ANODE
2. ANODE
3. CATHODE | STYLE 24:
PIN 1. GATE
2. DRAIN
3. SOURCE | STYLE 25:
PIN 1. ANODE
2. CATHODE
3. GATE | STYLE 26:
PIN 1. CATHODE
2. ANODE
3. NO CONNECTION |
| STYLE 27:
PIN 1. CATHODE
2. CATHODE
3. CATHODE | STYLE 28:
PIN 1. ANODE
2. ANODE
3. ANODE | | | | |

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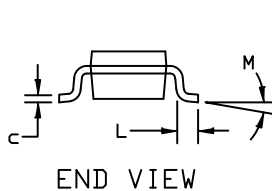
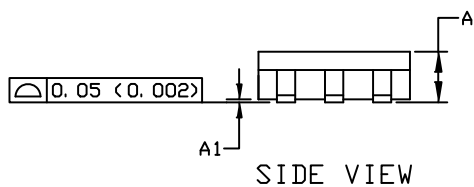
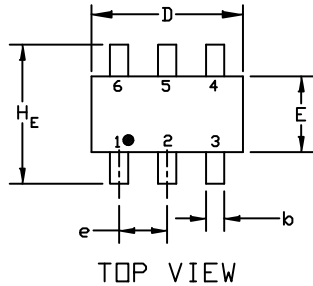
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



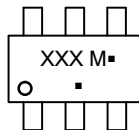
SCALE 2:1

SC-74
CASE 318F
ISSUE P

DATE 07 OCT 2021



GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
M = Date Code
▪ = Pb-Free Package

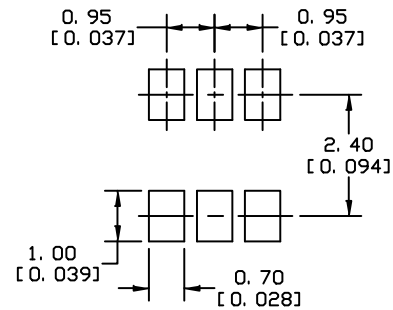
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NOTES:

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- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.

DIM	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.90	1.00	1.10	0.035	0.039	0.043
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.25	0.37	0.50	0.010	0.015	0.020
c	0.10	0.18	0.26	0.004	0.007	0.010
D	2.90	3.00	3.10	0.114	0.118	0.122
E	1.30	1.50	1.70	0.051	0.059	0.067
e	0.85	0.95	1.05	0.034	0.037	0.041
HE	2.50	2.75	3.00	0.099	0.108	0.118
L	0.20	0.40	0.60	0.008	0.016	0.024
M	0*	---	10*	0*	---	10*



* For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

SOLDERING FOOTPRINT

- | | | | | | |
|---|--|---|--|---|---|
| <p>STYLE 1:
PIN 1. CATHODE
2. ANODE
3. CATHODE
4. CATHODE
5. ANODE
6. CATHODE</p> | <p>STYLE 2:
PIN 1. NO CONNECTION
2. COLLECTOR
3. EMITTER
4. NO CONNECTION
5. COLLECTOR
6. BASE</p> | <p>STYLE 3:
PIN 1. EMITTER 1
2. BASE 1
3. COLLECTOR 2
4. EMITTER 2
5. BASE 2
6. COLLECTOR 1</p> | <p>STYLE 4:
PIN 1. COLLECTOR 2
2. EMITTER 1/EMITTER 2
3. COLLECTOR 1
4. EMITTER 3
5. BASE 1/BASE 2/COLLECTOR 3
6. BASE 3</p> | <p>STYLE 5:
PIN 1. CHANNEL 1
2. ANODE
3. CHANNEL 2
4. CHANNEL 3
5. CATHODE
6. CHANNEL 4</p> | <p>STYLE 6:
PIN 1. CATHODE
2. ANODE
3. CATHODE
4. CATHODE
5. CATHODE
6. CATHODE</p> |
| <p>STYLE 7:
PIN 1. SOURCE 1
2. GATE 1
3. DRAIN 2
4. SOURCE 2
5. GATE 2
6. DRAIN 1</p> | <p>STYLE 8:
PIN 1. EMITTER 1
2. BASE 2
3. COLLECTOR 2
4. EMITTER 2
5. BASE 1
6. COLLECTOR 1</p> | <p>STYLE 9:
PIN 1. EMITTER 2
2. BASE 2
3. COLLECTOR 1
4. EMITTER 1
5. BASE 1
6. COLLECTOR 2</p> | <p>STYLE 10:
PIN 1. ANODE/CATHODE
2. BASE
3. EMITTER
4. COLLECTOR
5. ANODE
6. CATHODE</p> | <p>STYLE 11:
PIN 1. EMITTER
2. BASE
3. ANODE/CATHODE
4. ANODE
5. CATHODE
6. COLLECTOR</p> | |

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